



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-09-18
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	giovanni giacopello	Representative title	APMS Material Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal statement

Supplier acceptance*	Legal declaration*	Standard
true		

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
L99VR033QTR	B0PL*URL3AQ3	A	996H	2024-09-18
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	7.00	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM01025218	
Package designator	Package size	Number of instances	Shape	
DSO	3x2x0.9	8	No lead	
Comment	VDFDN 3X2X0.9 8L WETT. FLANKS			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		True
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		False
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		False
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		False
Exemption Id.	Description	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		True
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		False
Exemption Id.	Description	

QueryList : California Prop65 list, dated 29th December 2023			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			False
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			True
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.009	die	1286

QueryList : REACH-27th June 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				True
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				True
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	False

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	True

Stockholm Convention Persistent Organic Pollutants	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	True

QueryList : EUSRR Directive	Response
Product contains hazardous materials listed in EUSRR Annex II	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B0PL*URL3AQ3					
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.966	mg	supplier	die	Silicon(Si)	7440-21-3		0.848	mg	877846	121141
				supplier	metallisation	Copper(Cu)	7440-50-8		0.077	mg	79710	11000
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.009	mg	9317	1286
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.003	mg	3106	429
				supplier	metallisation	Tungsten(W)	7440-33-7		0.004	mg	4141	571
				supplier	passivation	Silicon oxide	7631-86-9		0.012	mg	12422	1714
				supplier	polymer coating	polyimide	proprietary		0.013	mg	13458	1857
Leadframe	M-004 Copper and its alloys	5.310	mg	supplier	alloy	Copper (Cu)	7440-50-8		5.162	mg	972127	737429
				supplier	alloy	Iron(Fe)	7439-89-6		0.122	mg	22976	17429
				supplier	alloy	Zinc(Zn)	7440-66-6		0.008	mg	1507	1143
				supplier	alloy	Phosphorus(P)	7723-14-0		0.002	mg	377	286
				supplier	metallization	Silver (Ag)	7440-22-4		0.016	mg	3013	2286
				supplier	glue	Silver(Ag)	7440-22-4		0.127	mg	798743	18143
Die attach	M-011 Other inorganic materials	0.159	mg	supplier	glue	Methylene diacrylate polymer	42594-17-2		0.026	mg	163522	3714
				supplier	glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.004	mg	25157	571
				supplier	glue	Epoxy cyclohexylethytrimethoxysilane	3388-04-3		0.001	mg	6289	143
				supplier	glue	Bis(alpha-dimethylbenzyl) peroxide	80-43-3		0.001	mg	6289	143
				supplier	wire	Copper(Cu)	7440-50-8		0.030	mg	1000000	4286
Encapsulation	M-011 Other inorganic materials	0.275	mg	supplier	mold compound	Silica vitreous	60676-86-0		0.255	mg	927273	36429
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.011	mg	40000	1571
				supplier	mold compound	Phenol resin	29690-82-2		0.008	mg	29091	1143
				supplier	mold compound	Carbon black	1333-86-4		0.001	mg	3636	143
Connections coating	Solder	0.260	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.260	mg	1000000	37143